

1       Claim 6 (once amended). The optical write head according to claim 1, wherein at  
2       least two positioning pins are provided at predetermined positions on the substrate  
3       support member.

1       Claim 8 (once amended). A method of assembling [the] an optical write head  
2       [according to claim 7, wherein] comprising a substrate, and a plurality of light-  
3       emitting device array chips arranged on the substrate in a straight line or in a  
4       staggered layout so as to oppose a rod lens array, each of the light-emitting array  
5       device chips having a light-emitting device array, wherein the rod lens array, a  
6       substrate support member for supporting the substrate, and a driver circuit board  
7       are each secured directly to a support member, wherein at least two rotatable  
8       eccentric pins penetrating through the support member are provided so as to come  
9       into contact with the substrate support member, comprising the step of rotating the  
10      at least two eccentric pins [are rotated,] to thereby move the substrate  
11      support member kept in contact with the eccentric pins and adjust the distance  
12      between a light-emission section of the light-emitting device array and a light-  
13      incident end face of the rod lens array.

1       Claim 9 (once amended). A method of assembling [the] an optical write head  
2       [according to claim 1, wherein] comprising a substrate, and a plurality of light-  
3       emitting device array chips arranged on the substrate in a straight line or in a  
4       staggered layout so as to oppose a rod lens array, each of the light-emitting array  
5       device chips having a light-emitting device array, wherein the rod lens array, a  
6       substrate support member for supporting the substrate, and a driver circuit board  
7       are each secured directly to a support member, comprising the step of die-bonding  
8       the light-emitting device array chips [are die-bonded] to a predetermined location  
9       on the substrate support member while being positioned with respect to a  
10      reference plane of the substrate support member.

1       Claim 10 (once amended). An optical write head comprising a substrate, and a  
2       plurality of light-emitting device array chips arranged on the substrate in a straight  
3       line or in a staggered layout so as to oppose a [gradient index] rod lens array, each

4       of the light-emitting device array chips having a light-emitting device array,  
5       wherein the light-emitting device array chips are mounted directly on a flexible  
6       printed circuit sheet.

1       Claim 11 (once amended). The optical write head according to claim 10, wherein  
2       [the] a reverse surface of a light-emitting device array chip mount section of the  
3       flexible printed circuit sheet is disposed in close contact with a member having  
4       rigidity.

1       Claim 15 (once amended). The optical write head according to claim [10] 11,  
2       wherein reference position marks for specifying respective positions at which the  
3       light-emitting array chips are to be arranged are provided on a [the] surface of the  
4       member which has rigidity and [is] are disposed in close contact with the flexible  
5       printed circuit sheet.

1       Claim 30 (once amended). The optical write head according to claim [17] 18,  
2       wherein a frame of the rod lens array is formed from glass, and the metallic  
3       member is nickel alloy or titanium.

1       Claim 31 (once amended). The optical write head according to claim [17] 18,  
2       wherein the light-emitting device array is a self-scan-type light-emitting device  
3       array.

## REMARKS

Concurrently filed with this amendment is a request to approve drawing changes for Figures 8-13. Figures 9-13 are proposed to be amended to include the legend "PRIOR ART". In addition, Figures 8 and 9 are proposed to be amended to correct numeral identifiers to correspond with the patent specification text.

Spelling and grammatical errors have been corrected in the patent specification. No new matter has been added.

Claims 1, 3, 5, 6, 8-11, 15, and 30-31 have been amended. Claims 1-31 remain in the application. A check for \$168 is attached to satisfy the fee for two